TOSHIBA Photocoupler GaA{As Ired & Photo IC

6N137

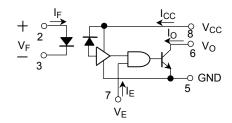
Degital Logic Isolation Tele-Communication Analog Data Equipment Control

The TOSHIBA 6N137 consist of a high emitting diode and a one chip photo IC. This unit is 8-lead DIP package.

- LSTTL / TTL compatible: 5V Supply
- Ultra high speed: 10MBd
- Guaranteed performance over temperature: 0°C to 70°C
- High isolation voltage: 2500Vrms min.
- UL recognized: UL1577, file no. E67349

Truth Table

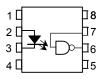
Input	Enable	Output
Н	Н	L
L	Н	Н
Н	L	Н
L	L	Н



6.4±0.25 고 3 2 3.65 +0.15 9.66 ± 0.25 7.62 ± 0.25 0.8 ± 0.25 1.2 ± 0.25+0. 0.5 ± 2.5MIN 7.85~8.80 2.54 ± 0.25 11-10C4 TOSHIBA 11-10C4

Weight: 0.54 g (typ.)

Pin Configurations (top view)



1 : N.C.

- 2 : Anode 3 : Cathode
- 4 : N.C.
- 5 : GND
- 6 : Output(Open collector)
- 7 : Enable 8 : V_{CC}
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Absolute Maximum Ratings

	Characteristic	Symbol	Rating	Unit
	Forward current		20	mA
LED	Pulse forward current (No	ote 1) I _{FP}	40	mA
	Reverse voltage	V _R	5	V
	Output current	Ι _Ο	50	mA
<u>ب</u>	Output voltage	Vo	7	V
Detector	Supply voltage (1 minute maximum)	V _{CC}	7	V
Det	Enable input voltage (not to exceed V _{CC} by more than 500mV)	V _{EH}	5.5	V
	Output collector power dissipation	Po	85	mW
Oper	Operating temperature range		0~70	°C
Storage temperature range		T _{stg}	-55~125	°C
Lead	solder temperature (10 s) (No	ote 2) T _{sol}	260	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1) 50% duty cycle, 1ms pulse width.

(Note 2) Soldering portion of lead: Up to 2mm from the body of the device.

Recommended Operating Conditions

Characteristic	Symbol	Min.	Max.	Unit
Input current, low level each channel	I _{FL}	0	250	μA
Input current, high level each channel	I _{FH}	7	20	mA
High level enable voltage	V _{EH}	2.0	V _{CC}	V
Low level enable voltage (output high)	V _{EL}	0	0.8	V
Supply voltage, output*	V _{CC}	4.5	5.5	V
Fan out (TTL load)	N	-	8	_
Operating temperature	Та	0	70	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

*This item denotes operating ranges, not meaning of recommended operating conditions.

Precaution

Please be careful of the followings.

A ceramic capacitor $(0.1\mu F)$ should be connected from pin 8 to pin 5 to stabilize the operation of the high gain linear amplifier. Failure to provide the bypassing may impair the switching property. The total lead length between capacitor and coupler should not exceed 1cm.

Electrical Characteristics Over Recommended Temperature (Ta = 0~70°C unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	(**)Typ.	Max.	Unit
High level output current	IOH	V_{CC} =5.5V, V_{O} =5.5V I _F =250 μ A, V_{E} = 2.0V	_	1	250	μΑ
Low level output voltage	V _{OL}	V _{CC} =5.5V, I _F =5mA V _{EH} =2.0V I _{OL} (sinking)=13mA	_	0.4	0.6	V
High level enable current	IEH	V _{CC} =5.5V, V _E =2.0V		-1.0		mA
Low level enable current	IEL	V _{CC} =5.5V, V _E =0.5V	_	-1.6	-2.0	mA
High level supply current	ICCH	V _{CC} =5.5V, I _F =0, V _E =0.5V	_	7	15	mA
Low level supply current	ICCL	V _{CC} =5.5V, I _F =10mA V _E =0.5V	_	12	18	mA
Resistance (input–output) (Note 3)	R _{I-O}	V _{I−O} =500V, Ta=25°C R.H.≤60%	_	10 ¹²	_	Ω
Capacitance (input–output) (Note 3)	C _{I–O}	f=1MHz, Ta=25°C	_	0.6	_	pF
Input forward voltage	VF	I _F =10mA, Ta=25°C	_	1.65	1.75	V
Input reverse breakdown voltage	BV _R	I _R =10µА, Та=25°С	5	_	_	V
Input capacitance	C _{IN}	V _F =0, f=1MHz	_	45	_	pF
Current transfer ratio	CTR	I _F =5.0mA, R _L =100Ω	_	1000	_	%

(**) All typical values are at V_{CC}=5V, Ta=25°C

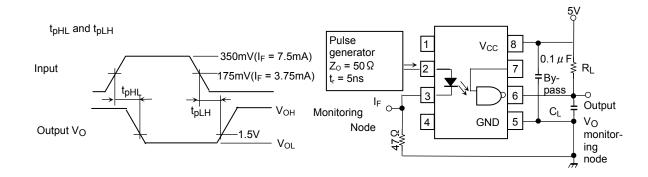
(Note 3) Pins 1, 2, 3 and 4 shorted together and pins 5, 6, 7 and 8 shorted together.

Switching Characteristics (Ta = 25°C, V_{CC} = 5V)

Characteristic	Symbol	Test Circuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time to high output level	t _p LH	1	R _L =350Ω, C _L =15pF I _F =7.5mA	_	60	75	ns
Propagation delay time to low output level	t _p HL	1	R _L =350Ω, C _L =15pF I _F =7.5mA	_	60	75	ns
Output rise–fall time (10–90%)	t _r , t _f	_	R _L =350Ω, C _L =15pF I _F =7.5mA	_	30	_	ns
Propagation delay time of enable from $V_{\mbox{EH}}$ to $V_{\mbox{EL}}$	telh	2	$R_L=350\Omega, C_L=15pF$ IF=7.5mA VEH=3.0V VEL=0.5V	_	25	_	ns
Propagation delay time of enable from $V_{\mbox{EL}}$ to $V_{\mbox{EH}}$	tEHL	2	$R_L=350\Omega, C_L=15pF$ I _F =7.5mA V _{EH} =3.0V V _{EL} =0.5V	_	25	-	ns
Common mode transient immunity at logic high output level	CMH	3	$\begin{array}{l} V_{CM} = 10V \\ R_L = 350\Omega \\ V_{O(min.)} = 2V \\ I_F = 0mA \end{array}$	_	200	_	V / μs
Common mode transient Immunity at logic low output level	CML	3	$\begin{array}{l} V_{CM} = 10V \\ R_L = 350\Omega \\ V_{O(max.)} = 0.8V \\ I_F = 5mA \end{array}$	_	-500	_	V / μs

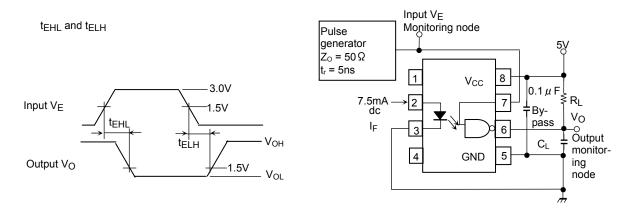
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Test Circuit 1.



 \cdot CL is approximately 15pF which includes probe and stray wiring capacitance.

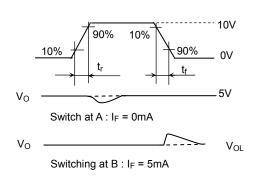
Test Circuit 2.

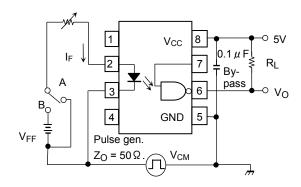


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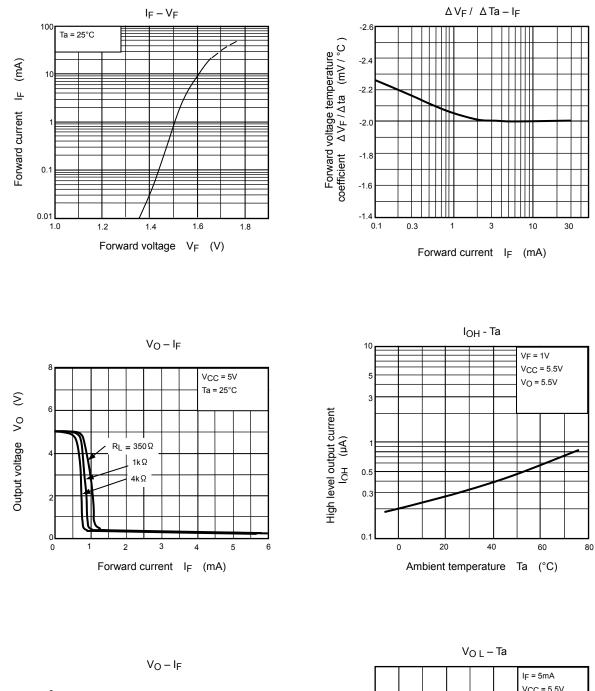
Test Circuit 3.

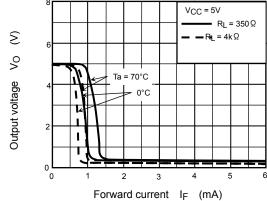
Transient immunity and typical waveforms





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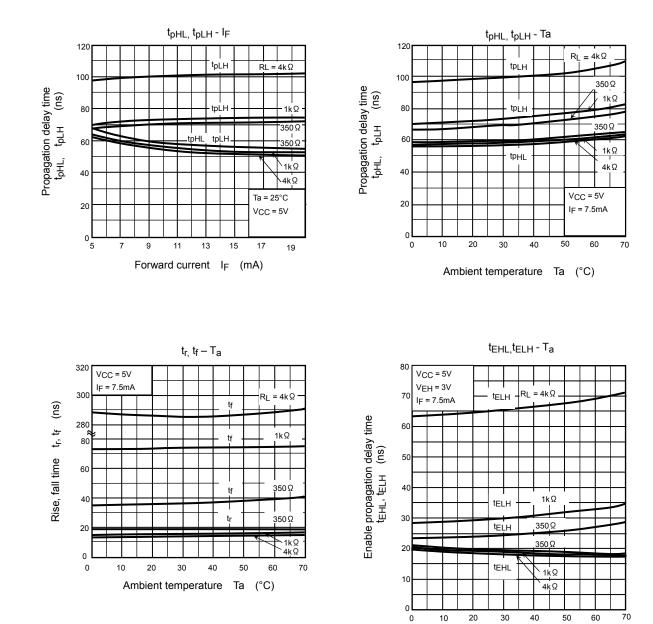




VCC = 5.5V 0.5 VE = 2V Low level output voltage VoL (V) IOL = 16mA 0.4 12.8mA 9.6mA 6.4mA 0.3 0.2 0 20 40 60 80 Ambient temperature Ta (°C)

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Ambient temperature Ta (°C)

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